

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) A smart ~~Smart~~ card ~~including~~ comprising:

a microcircuit,

one or more other components, including an accessible component, and

an external contacts in a card support, ~~characterized in that wherein~~ the microcircuit (1), the accessible component (2) and the external contacts (12) form part of a subassembly (S1, S2) fixed in a housing (C1+C2+C3) formed in a portion of the thickness of the card support, that subassembly including a support film (10) carrying on an internal face the microcircuit (1) and at least the accessible component (2) and on an external face the external contacts (12), a window being formed in the support film facing a portion of the accessible component.

2. (currently amended) The smart ~~Smart~~ card according to ~~Claim~~ claim 1, ~~characterized in that wherein~~ the subassembly further includes an interface component (3) connected between the microcircuit (1) and the accessible component (2).

3. (currently amended) The smart ~~Smart~~-card according to ~~Claim~~ claim 2, ~~characterized in that wherein~~ the interface component is a controller for the accessible component.

4. (currently amended) The smart ~~Smart~~-card according to claim 1, ~~characterized in that wherein~~ the connections within the subassembly are made by connecting wires (7, 8, 9).

5. (currently amended) The smart ~~Smart~~-card according to ~~Claim~~ claim 4, ~~characterized in that wherein~~ each connecting wire is connected, firstly, to the microcircuit (1) or to a component (2, 3), and, secondly, to a connecting track (4, 5) carried by the support film.

6. (currently amended) The smart ~~Smart~~-card according to claim 1, ~~characterized in that wherein~~ the housing includes at least one cavity (C1) in which the microcircuit (1) is fixed and one cavity (C2) in which the accessible component (2) is fixed, at least one rib (15, 16) being provided between the cavities.

7. (currently amended) The smart ~~Smart~~-card according to ~~Claim~~ claim 6, ~~characterized in that wherein~~ the support film includes an area mechanically weakened in bending between at least the microcircuit and a component and adapted to bear against a rib.

8. (currently amended) The smart ~~Smart~~-card according to ~~Claim~~ claim 7, ~~characterized in that wherein~~ a mechanically weakened area is formed on either side of the microcircuit and of each component.

9. (currently amended) The smart ~~Smart~~-card according to ~~Claim~~ claim 7, ~~characterized in that wherein~~ each mechanically weakened area includes at least one slot (F1 to F6).

10. (currently amended) The smart ~~Smart~~-card according to claim 6, ~~characterized in that wherein~~ connecting tracks (4, 5) are formed between the microcircuit and each component, each track facing a rib and being crossed by at least one mechanically weakened area.

11. (currently amended) The smart ~~Smart~~-card according to claim 6, ~~characterized in that wherein~~ each cavity is filled with a rigid material containing the microcircuit or a component and extending as far as the support film.

12. (currently amended) The smart ~~Smart~~-card according to ~~Claim~~ claim 9, ~~characterized in that wherein~~ each cavity is provided at the periphery of its bottom with at least one depression (18).

13. (currently amended) A method ~~Method~~ of fabricating a smart card including a microcircuit and at least one other component including an accessible component, the method ~~including the following steps comprising:~~

- assembling a subassembly (S1 or S2) by mounting on a support film (10) the microcircuit (1) and at least the accessible component (2), providing in the film a window (11) for access to the accessible component, and making the connections by means of connecting wires,
- forming a housing (C1+C2+C3) in the card support,
- fixing the subassembly in the housing.

14. (currently amended) The method ~~Method~~ according to ~~Claim claim~~ 13, ~~characterized in that wherein~~ a cavity (C1) for the microcircuit (1) and a cavity (C2) for the accessible component (2) are formed in the housing.

15. (currently amended) The method ~~Method~~ according to ~~Claim claim~~ 14, ~~characterized in that wherein~~ areas mechanically weakened in bending (F2, F3, F4, F5) are formed in the support film at least between the microcircuit and the accessible component.

16. (currently amended) The method ~~Method~~ according to ~~Claim~~ claim 15, ~~characterized in that wherein~~ areas mechanically weakened in bending are formed in the support film on either side of the microcircuit and of each component.

17. (currently amended) The method ~~Method~~ according to ~~Claim~~ claim 15, ~~characterized in that wherein~~ the areas mechanically weakened in bending are formed by slots (F1, ..., F6).

18. (currently amended) The method ~~Method~~ according to claim 14, ~~characterized in that wherein~~ at least one area mechanically weakened in bending is disposed facing a rib (15, 16) formed in the housing between two cavities.

19. (currently amended) The method ~~Method~~ according to claim 14, ~~characterized in that wherein~~ connecting tracks (4, 5) connected by wires to the microcircuit or to a component are crossed by the areas mechanically weakened in bending.

20. (currently amended) The method ~~Method~~ according to claim 14, ~~characterized in that wherein~~ at least one depression (18) is formed at the periphery of the bottom of at least one cavity.